

International Application No.: PCT/JP2004/017173
U.S. Patent Application No.: Unknown
April 15, 2005
Page 3 of 10

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

ABSTRACT OF THE DISCLOSURE

A laminated ceramic electronic component includes a plurality of conductor pattern layers ~~(2, 3, and 4)~~ for a coil ~~overlaps~~arranged to overlap each other to form substantially U-shaped conductors ~~(2A, 3A, and 4A)~~ for the coil. The conductors ~~(2A, 3A, and 4A)~~ for the coil are electrically connected in series ~~with~~through via holes ~~(15)~~ for interinner layer connection provided in ceramic green sheets ~~(10 and 11)~~ to form a spiral coil ~~(L)~~. A plurality of leading conductor pattern layers ~~(5 and 6)~~ also overlaps each other to form leading conductors ~~(5A and 6A)~~. One leading conductor pattern layer ~~(5)~~ is disposed per a predetermined number of conductor pattern layers ~~(2)~~ for the coil. An end ~~(51)~~ of each leading conductor pattern layer ~~(5)~~ is in contact with the corresponding conductor pattern layer ~~(2)~~ for the coil. In other words, the thickness of the leading conductors ~~(5A and 6A)~~ is ~~smaller~~less than the thickness of the conductors ~~(2A to 4A)~~ for the coil.